

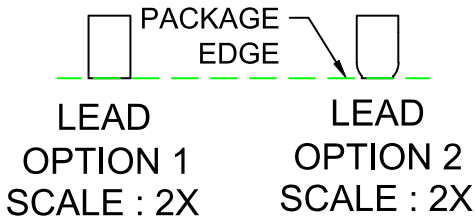
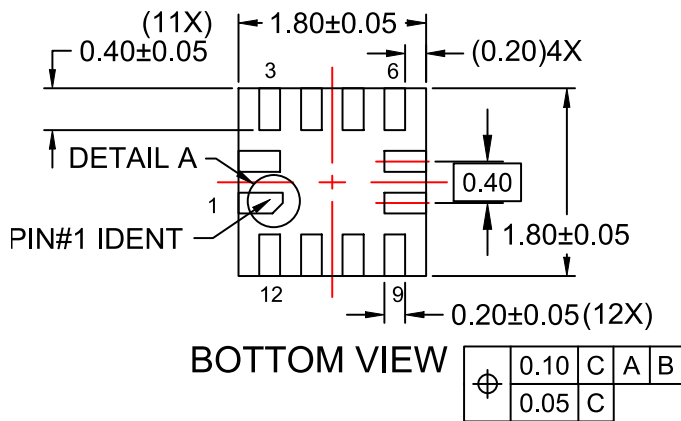
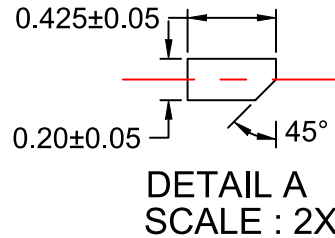
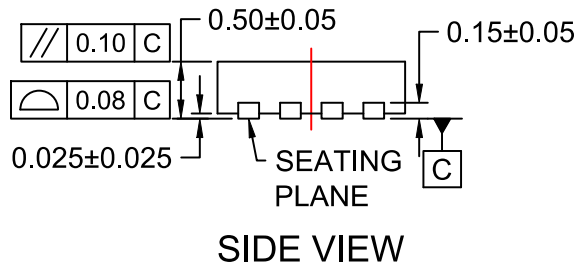
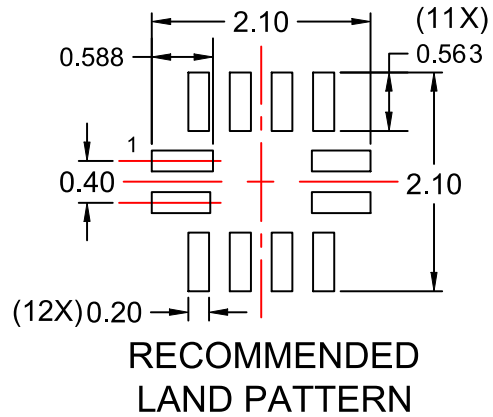
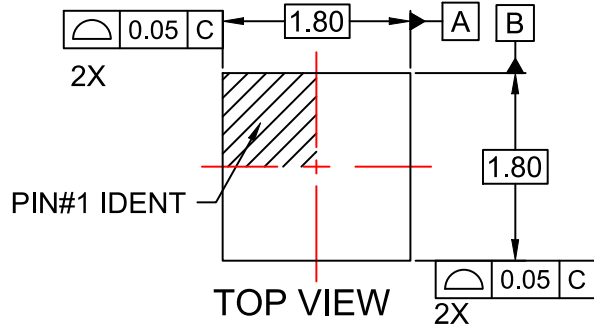
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

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UQFN12 1.8x1.8, 0.4P
CASE 523BE
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DATE 31 OCT 2016



NOTES:

- A. PACKAGE DOES NOT CONFORM TO ANY JEDEC STANDARD.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.

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